

HSEC8-160-01-S-DV-A

0,80mm HI-SPEED SOCKET HSEC8 SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material:

Black Liquid Crystal Polymer



Contact:

BeCu
Plating:
Au or Sn over 50µ" (1,27µm) Ni



Current Rating:

3.1A @ 30°C Temperature Rise

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(3,15mm) .125" nominal

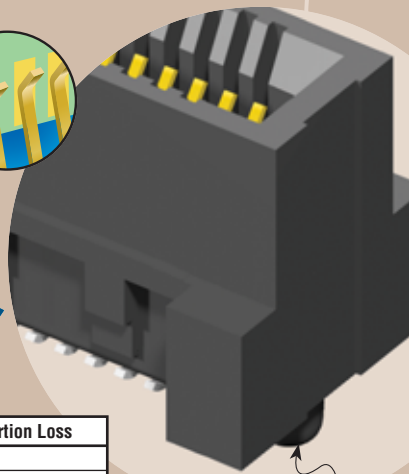
RoHS Compliant:

Yes

Processing:

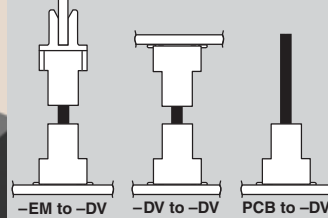
Max Processing Temp:
230°C for 60 seconds, or
260°C for 20 seconds
Lead-Free Solderable: Yes
SMT Lead Coplanarity:
(0,10mm) .004" max (10-60)

Mates with:
1,6mm thick cards,
EEDP, HSC8, HSF8

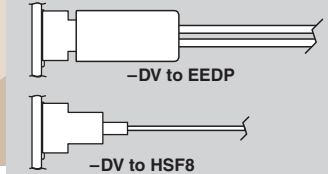


Alignment Pins

BOARD-TO-BOARD APPLICATIONS



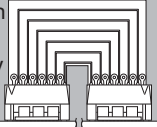
HIGH SPEED CABLE & FLEX APPLICATIONS



| | |
|---|-----------------------------|
| 0,80mm HSEC8 | Rated @ -3dB Insertion Loss |
| 7,98mm Stack Height | |
| Single-Ended Signaling | 8 GHz / 16 Gbps |
| Differential Pair Signaling | 10.5 GHz / 21 Gbps |
| For complete test data go to www.samtec.com?HSEC8 or contact sig@samtec.com | |

STANDARD & CUSTOM CARDS AVAILABLE

- Standard high speed interface cards for 19mm, 25mm & 30mm mated heights, single-ended & differential applications. See HSC8 Series.
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes



APPLICATION SPECIFIC OPTION



Note: Other Gold plating options available. Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

HSEC8 - 1 POSITIONS PER ROW - CARD THICKNESS - PLATING OPTION - DV - A - OTHER OPTION

10, 13, 20, 25, 30, 37, 40, 49, 50, 60

-01 = (1,60mm) .062" thick card

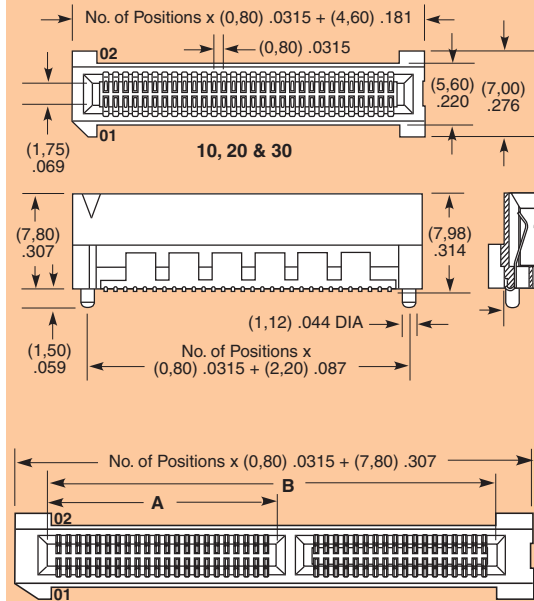
-S = 30µ" (0,76µm) Gold on contact, Matte Tin on tail

-K = (5,50mm) .217" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel Packaging

-L = Latching Option (For use with EEDP.) (13, 25, 37, 49 only)

-BL = Board Locks (40, 50, 60 only)



| POSITIONS PER ROW | A | B |
|-------------------|---------------|---------------|
| 13* | (6,10) .240 | (15,00) .591 |
| 25* | (6,10) .240 | (24,60) .969 |
| 37* | (18,10) .713 | (34,20) 1.346 |
| 40 | (18,90) .744 | (36,60) 1.441 |
| 49* | (22,90) .902 | (43,80) 1.724 |
| 50 | (22,90) .902 | (44,60) 1.756 |
| 60 | (26,90) 1.059 | (52,60) 2.071 |

Positions where no dimensions are given do not have keying feature.
*Mates with EEDP Series.

| CONNECTOR | CABLE* |
|-----------|---------|
| HSEC8-113 | EEDP-08 |
| HSEC8-125 | EEDP-16 |
| HSEC8-137 | EEDP-24 |
| HSEC8-149 | EEDP-32 |

Due to technical progress, all designs, specifications and components are subject to change without notice.

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